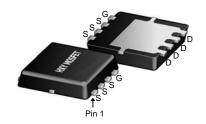


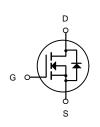
### **General Description**

The SIR882BDP-T1-RE3 use advanced SGT MOSFET technology to provide low RDS(ON), low gate charge, fast switching and excellent avalanche characteristics.

This device is specially designed to get better ruggedness.



DFN5X6-8L (Power(5x6))



N-Channel MOSFET

#### **General Features**

 $V_{DS} = 100V I_{D} = 75A$ 

 $R_{DS(ON)} < 7.5 \text{m}\Omega$   $V_{GS}=10V$ 

### **Applications**

Consumer electronic power supply Motor control

Synchronous-rectification Isolated DC

Synchronous-rectification applications

#### **Package Marking and Ordering Information**

Product ID	Pack	Brand	Qty(PCS)
SIR882BDP-T1-RE3	DFN5X6-8L(Power(5x6))	HXY MOSFET	5000

### Absolute Maximum Ratings at T<sub>j</sub>=25°C unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	VDS	100	V
Gate source voltage	VGS	±20	V
Continuous drain current <sup>1)</sup>	ID	75	А
Pulsed drain current <sup>2)</sup>	ID, pulse	300	А
Power dissipation <sup>3)</sup>	P <sub>D</sub>	97	W
Single pulsed avalanche energy <sup>5)</sup>	EAS	90	mJ
Operation and storage temperature	Tstg,Tj	-55 to 150	°C
Thermal resistance, junction-case	RθJC	1.3	°C/W



## Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise specified)

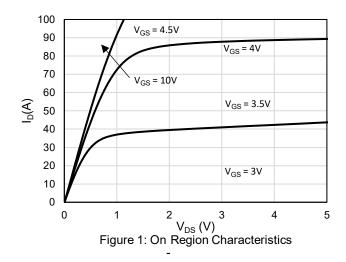
Symbol	Parameter	Parameter Test Condition		Тур.	Max.	Units
Off Charac	cteristic					
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	100	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V, -		-	1.0	μA
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> = ±20V -		-	±100	nA
On Charac	cteristics			•		
$V_{GS(th)}$	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.0	1.6	2.5	V
В	Static Drain-Source on-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =20A -		6.4	7.5	mΩ
$R_{DS(on)}$	note3	V <sub>GS</sub> =4.5V, I <sub>D</sub> =8A -		9.2	11.4	mΩ
Dynamic (	Characteristics			•		
C <sub>iss</sub>	Input Capacitance		-	2944	-	pF
Coss	Output Capacitance	V <sub>DS</sub> =50V, V <sub>GS</sub> =0V,	-	736	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	f=1.0MHz	-	2.04	-	pF
Qg	Total Gate Charge	)/ 50\/ L 00A	_	39.4	-	nc
Q <sub>gs</sub>	Gate-Source Charge	$V_{DS}$ =50V, $I_{D}$ =30A, $V_{GS}$ =10V	-	5.6	-	nc
$Q_{\text{gd}}$	Gate-Drain("Miller") Charge	VGS-10V	-	7.6	-	nc
Switching	Characteristics					
t <sub>d(on)</sub>	Turn-on Delay Time		_	13	-	nc
t <sub>r</sub>	Turn-on Rise Time	V <sub>DD</sub> =50V, I <sub>D</sub> =25A,	_	27.5	-	nc
t <sub>d(off)</sub>	Turn-off Delay Time	R <sub>G</sub> =6Ω, V <sub>GS</sub> =10V	_	45.5	-	nc
t <sub>f</sub>	Turn-off Fall Time		_	41.5	-	nc
Drain-Sou	rce Diode Characteristics and Maxim	um Ratings				
Is		Maximum Continuous Drain to Source Diode Forward		_	75	Α
		Current				
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current			-	300	Α
$V_{\text{SD}}$	Drain to Source Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =30A	-	-	1	V
t <sub>rr</sub>	Body Diode Reverse Recovery Time	T -25°0	-	177	-	ns
Qrr	Body Diode Reverse Recovery Charge	T <sub>J</sub> =25°C, I <sub>F</sub> =12A,dI/dt=100A/μs	-	1291	-	nc

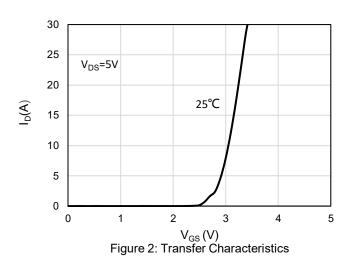
Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

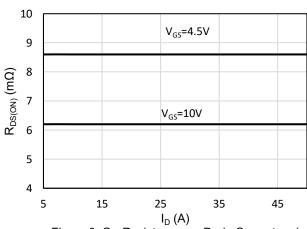
- 2. EAS condition:  $T_J$ =25°C,  $V_{DD}$ =50V,  $V_G$ =10V,  $R_G$ =25 $\Omega$ , L=0.5mH,  $I_{AS}$ =19A
- 3. Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%

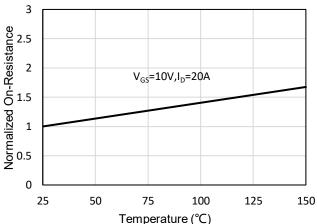


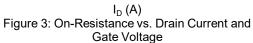
### **Typical Performance Characteristics**

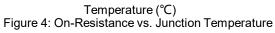


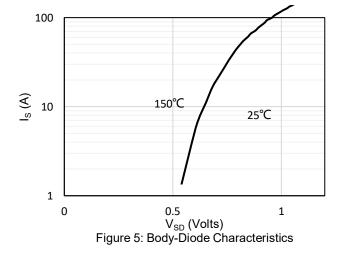


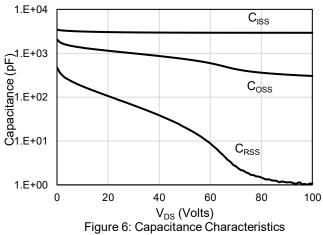




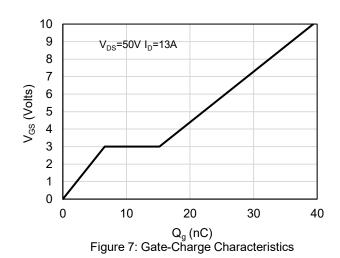


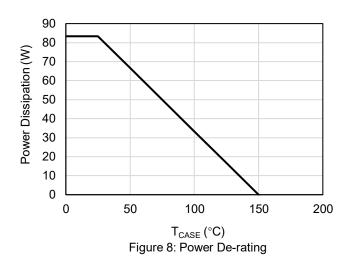


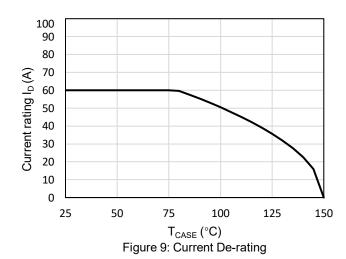




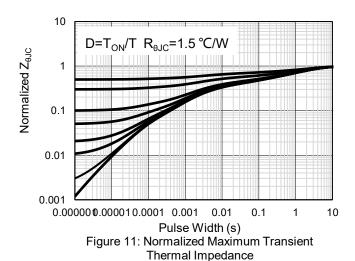












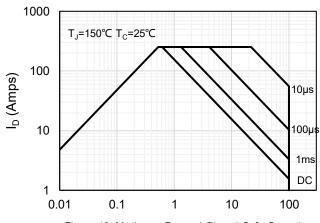
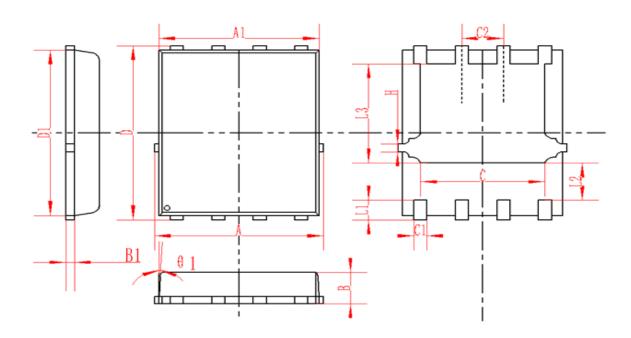


Figure 12: Maximum Forward Biased Safe Operating Area



# DFN5X6-8L(Power(5x6)) Package Information



SYMBOL	MM		INCH			
STIVIDOL	MIN	NOM	MAX	MIN	NOM	MAX
А	4.95	5	5.05	0.195	0.197	0.199
A1	4.82	4.9	4.98	0.190	0.193	0.196
D	5.98	6	6.02	0.235	0.236	0.237
D1	5.67	5.75	5.83	0.223	0.226	0.230
В	0.9	0.95	1	0.035	0.037	0.039
B1	0.254REF		0.010REF			
С	3.95	4	4.05	0.156	0.157	0.159
C1	0.35	0.4	0.45	0.014	0.016	0.018
C2		1.27TYP			0.5TYP	
θ1	8°	10°	12°	8°	10°	12°
L1	0.63	0.64	0.65	0.025	0.025	0.026
L2	1.2	1.3	1.4	0.047	0.051	0.055
L3	3.415	3.42	3.425	0.134	0.135	0.135
Η	0.24	0.25	0.26	0.009	0.010	0.010



### Attention

- Any and all HUA XUAN YANG ELECTRONICS products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your HUA XUAN YANG ELECTRONICS representative nearest you before using any HUA XUAN YANG ELECTRONICS products described or contained herein in such applications.
- HUA XUAN YANG ELECTRONICS assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein.
- Specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- HUA XUAN YANG ELECTRONICS CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all HUA XUAN YANG ELECTRONICS products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of HUA XUAN YANG ELECTRONICS CO.,LTD.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production.

  HUA XUAN YANG ELECTRONICS believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the HUA XUAN YANG ELECTRONICS product that you intend to use.